US00D366246S

United States Patent [19]

Simek et al.

[11] **Patent Number: Des. 366,246**

[45] **Date of Patent: **Jan. 16, 1996**

---

[54] **FRONT PANEL FOR ENCLOSING ELECTRONIC CIRCUIT PACKS**

[75] Inventors: **Robert F. Simek**, Lakewood; **Thomas J. McClaughry**, Hoffman Estates, both of Ill.

[73] Assignee: **Motorola, Inc.**, Schaumburg, Ill.

[**] Term: **14 Years**

[21] Appl. No.: **19,158**

[22] Filed: **Feb. 24, 1994**

[52] **U.S. Cl.** **D13/177**; D10/125

[58] **Field of Search** D13/158, 177; 200/43.22, 333, 334; 439/519, 528, 536; 174/66, 67; 220/3.4, 3.8, 241, 242; D10/103, 125

[56] **References Cited**

U.S. PATENT DOCUMENTS

D. 190,233	5/1961	Spadaro	D13/177
D. 308,679	6/1990	Reshanov	D13/177
D. 312,611	12/1990	Watson et al.	D13/158
2,620,080	12/1952	Tomlin	220/3.4
3,058,020	10/1962	Balan	174/66
3,233,071	2/1966	Buzzell	300/333

Primary Examiner—A. Hugo Word

[57] **CLAIM**

The ornamental design for a front panel for enclosing electronic circuit packs, as shown and described.

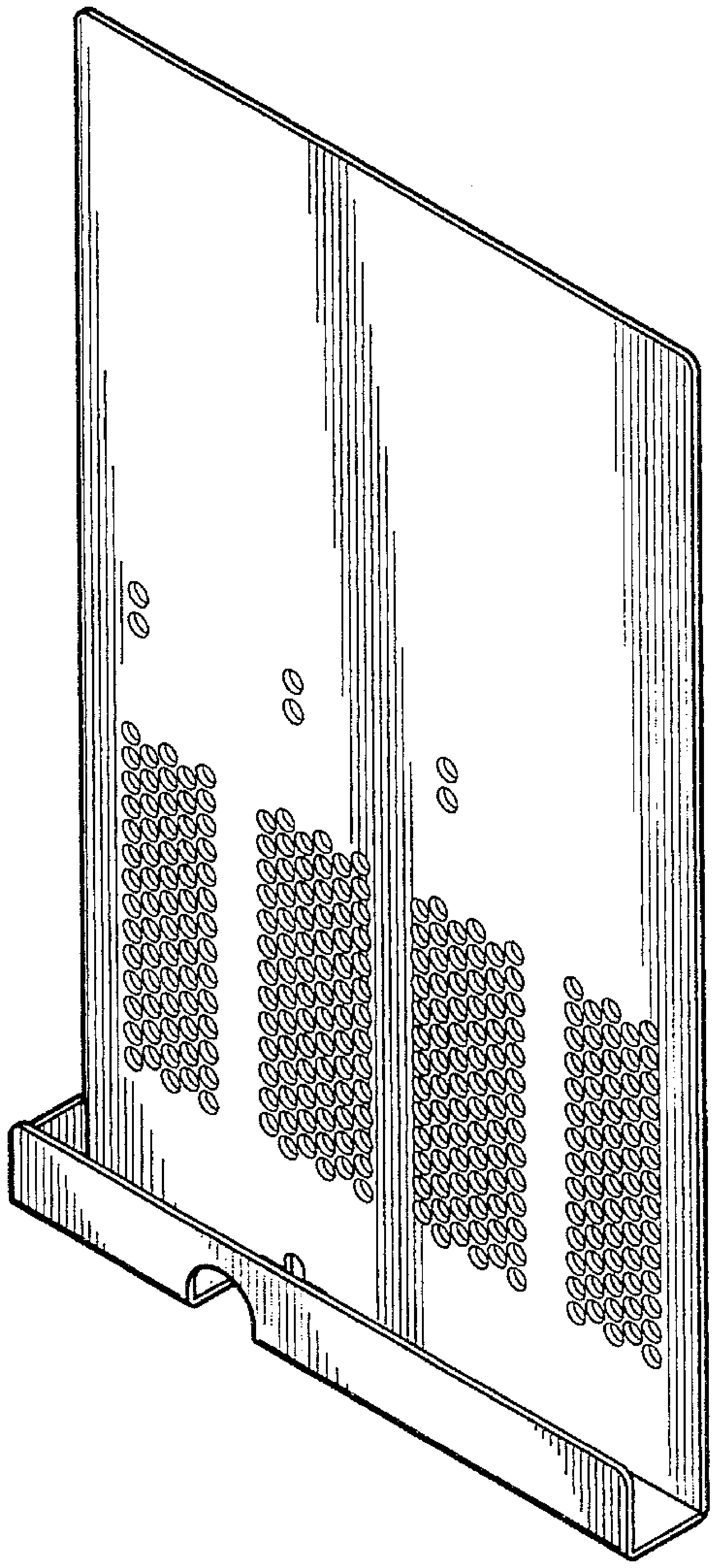
DESCRIPTION

FIG. **1** is a front, top, and right side perspective view of a front panel for enclosing electronic circuit packs showing our new design;

FIG. **2** is a left side elevational view thereof; and,

FIG. **3** is a bottom plan view thereof.

1 Claim, 1 Drawing Sheet



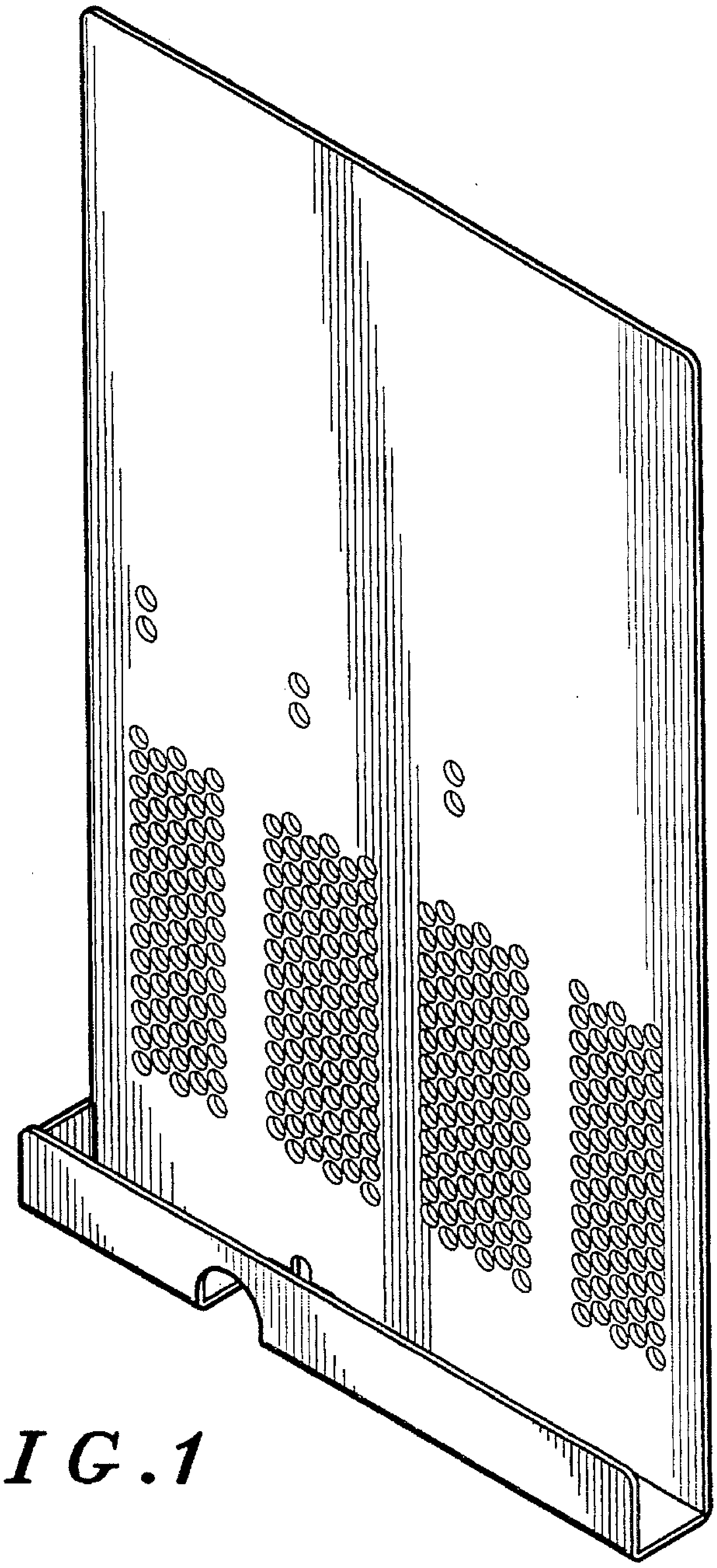


FIG. 1

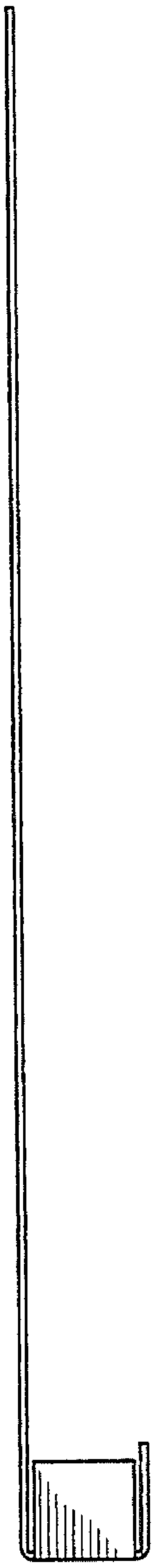


FIG. 2

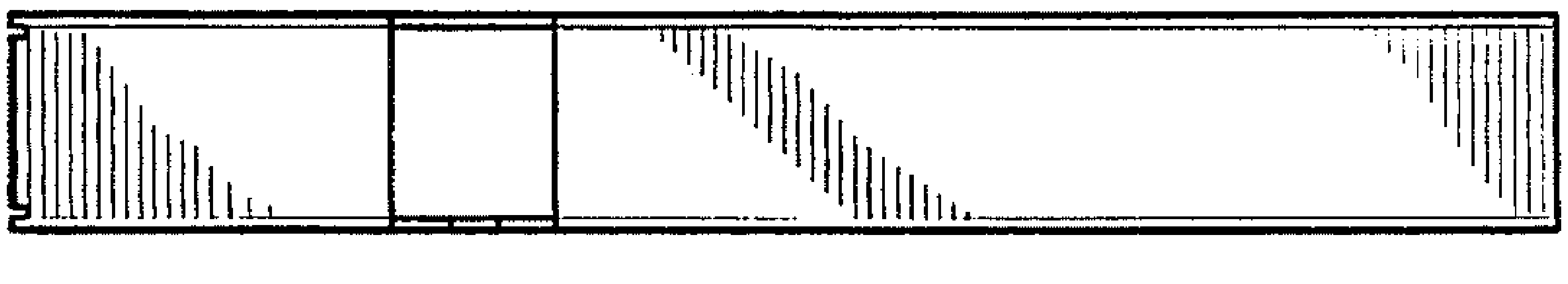


FIG. 3